**Product data sheet** 

# 1. General description

Planar passivated high commutation three quadrant triac in a SOT78 (TO-220AB) plastic package. This "series D" triac balances the requirements of commutation performance and gate sensitivity. The "very sensitive gate" "series D" is intended for interfacing with low power drivers including microcontrollers.

### 2. Features and benefits

- 3Q technology for improved noise immunity
- Direct interfacing with low power drivers and microcontrollers
- Good immunity to false turn-on by dV/dt
- · High commutation capability with very sensitive gate
- · High voltage capability
- · Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- · Very sensitive gate for easy logic level triggering

## 3. Applications

- Electronic thermostats (heating and cooling)
- · High power motor controls e.g. washing machines and vacuum cleaners

### 4. Quick reference data

Table 1. Quick reference data

| Symbol              | Parameter                                | Conditions                                                                                                                               | Min | Тур | Max | Unit |
|---------------------|------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------|-----|-----|-----|------|
| $V_{DRM}$           | repetitive peak off-<br>state voltage    |                                                                                                                                          | -   | -   | 600 | V    |
| I <sub>T(RMS)</sub> | RMS on-state current                     | full sine wave; $T_{mb} \le 100 ^{\circ}\text{C}$ ; $\overline{\text{Fig. 1}}$ ; $\overline{\text{Fig. 2}}$ ; $\overline{\text{Fig. 3}}$ | -   | -   | 12  | А    |
| I <sub>TSM</sub>    | non-repetitive peak on-<br>state current | full sine wave; $T_{j(init)} = 25 ^{\circ}\text{C}$ ;<br>$t_p = 20  \text{ms}$ ; Fig. 4; Fig. 5                                          | -   | -   | 100 | А    |
|                     |                                          | full sine wave; $T_{j(init)}$ = 25 °C;<br>$t_p$ = 16.7 ms                                                                                | -   | -   | 110 | А    |
| Tj                  | junction temperature                     |                                                                                                                                          | -   | -   | 125 | °C   |
| Static charact      | eristics                                 |                                                                                                                                          |     |     |     |      |
| I <sub>GT</sub>     | gate trigger current                     | $V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2+ G+;$<br>$T_j = 25 \text{ °C; } Fig. 7$                                                   | -   | -   | 5   | mA   |
|                     |                                          | $V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$<br>$T_j = 25 \text{ °C; } Fig. 7$                                                  | -   | -   | 5   | mA   |

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| Symbol                | Parameter                             | Conditions                                                                                                              | Min | Тур | Max | Unit |
|-----------------------|---------------------------------------|-------------------------------------------------------------------------------------------------------------------------|-----|-----|-----|------|
|                       |                                       | $V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$<br>$T_j = 25 \text{ °C; } \frac{\text{Fig. 7}}{}$                   | -   | -   | 5   | mA   |
| I <sub>H</sub>        | holding current                       | V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>                                                            | _   | -   | 10  | mA   |
| $V_{T}$               | on-state voltage                      | I <sub>T</sub> = 15 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>                                                           | -   | 1.3 | 1.6 | V    |
| Dynamic ch            | naracteristics                        |                                                                                                                         |     |     |     |      |
| dV <sub>D</sub> /dt   | rate of rise of off-state voltage     | $V_{DM}$ = 402 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit              | 20  | -   | -   | V/µs |
| dl <sub>com</sub> /dt | rate of change of commutating current | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 12 A; $dV_{com}/dt$ = 20 V/µs; (snubberless condition); gate open circuit | 1   | -   | -   | A/ms |
|                       |                                       | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 12 A; $dV_{com}/dt$ = 10 V/ $\mu$ s; gate open circuit                    | 1.5 | -   | -   | A/ms |
|                       |                                       | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 12 A; $dV_{com}/dt$ = 1 V/ $\mu$ s; gate open circuit                     | 4.5 | -   | -   | A/ms |

# 5. Pinning information

**Table 2. Pinning information** 

| Pin | Symbol | Description                    | Simplified outline     | Graphic symbol |
|-----|--------|--------------------------------|------------------------|----------------|
| 1   | T1     | main terminal 1                | mb                     | T2             |
| 2   | T2     | main terminal 2                | <b>├</b>               | G<br>sym051    |
| 3   | G      | gate                           |                        | symosi         |
| mb  | T2     | mounting base; main terminal 2 | 1 2 3 TO-220AB (SOT78) |                |
|     |        |                                | TO-220AB (SOT78)       |                |

# 6. Ordering information

**Table 3. Ordering information** 

| Type number | Package  |                                                                                  |         |  |  |  |
|-------------|----------|----------------------------------------------------------------------------------|---------|--|--|--|
|             | Name     | Description                                                                      | Version |  |  |  |
| BTA312-600D | TO-220AB | plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB | SOT78   |  |  |  |

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# 7. Limiting values

### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol              | Parameter                                | Conditions                                                                 | Min | Max | Unit |
|---------------------|------------------------------------------|----------------------------------------------------------------------------|-----|-----|------|
| $V_{DRM}$           | repetitive peak off-state voltage        |                                                                            | -   | 600 | V    |
| I <sub>T(RMS)</sub> | RMS on-state current                     | full sine wave; $T_{mb} \le 100 ^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3 | -   | 12  | Α    |
| I <sub>TSM</sub>    | non-repetitive peak on-<br>state current | full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 20 ms;<br>Fig. 4; Fig. 5    | -   | 100 | Α    |
|                     |                                          | full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 16.7 ms     | -   | 110 | Α    |
| I <sup>2</sup> t    | I <sup>2</sup> t for fusing              | t <sub>p</sub> = 10 ms; SIN                                                | -   | 50  | A²s  |
| dl <sub>T</sub> /dt | rate of rise of on-state current         | I <sub>G</sub> = 0.2 A                                                     | -   | 100 | A/µs |
| I <sub>GM</sub>     | peak gate current                        |                                                                            | -   | 2   | Α    |
| P <sub>GM</sub>     | peak gate power                          |                                                                            | -   | 5   | W    |
| P <sub>G(AV)</sub>  | average gate power                       | over any 20 ms period                                                      | -   | 0.5 | W    |
| T <sub>stg</sub>    | storage temperature                      |                                                                            | -40 | 150 | °C   |
| Tj                  | junction temperature                     |                                                                            | -   | 125 | °C   |

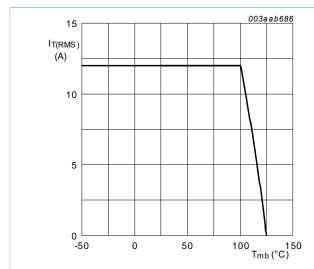


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

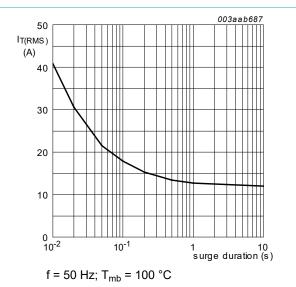


Fig. 2. RMS on-state current as a function of surge duration; maximum values

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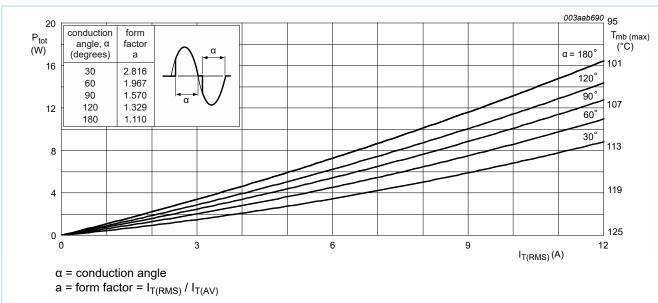


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

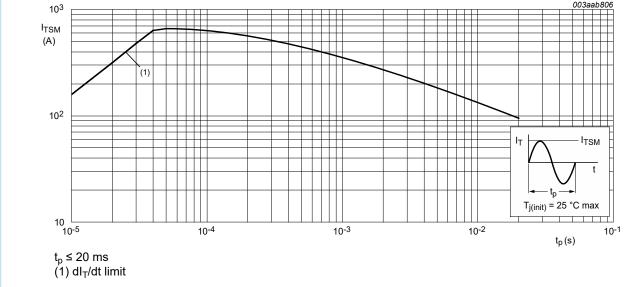


Fig. 4. Non-repetitive peak on-state current as a function of pulse duration; maximum values

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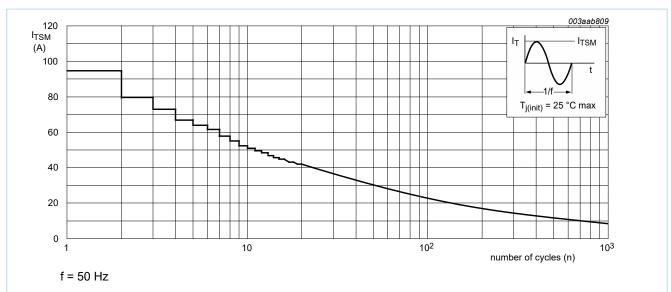


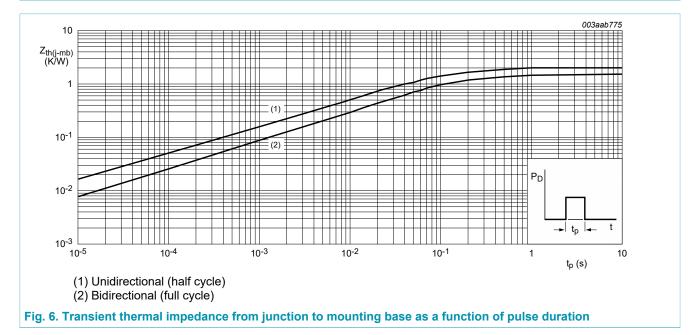
Fig. 5. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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## 8. Thermal characteristics

**Table 5. Thermal characteristics** 

| Symbol                                                                 | Parameter                                                  | Conditions         | Min | Тур | Max | Unit |
|------------------------------------------------------------------------|------------------------------------------------------------|--------------------|-----|-----|-----|------|
| R <sub>th(j-mb)</sub> thermal resistant from junction to mounting base |                                                            | full cycle; Fig. 6 | -   | -   | 1.5 | K/W  |
|                                                                        | _                                                          | half cycle; Fig. 6 | -   | -   | 2   | K/W  |
| $R_{th(j-a)}$                                                          | thermal resistance<br>from junction to<br>ambient free air | in free air        | -   | 60  | -   | K/W  |



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## 9. Characteristics

### Table 6. Characteristics

| Symbol                | Parameter                                                                             | Conditions                                                                                                              | Min  | Тур | Max | Unit |
|-----------------------|---------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------|------|-----|-----|------|
| Static char           | acteristics                                                                           |                                                                                                                         | '    |     |     | ,    |
| I <sub>GT</sub>       | gate trigger current                                                                  | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+;$<br>$T_j = 25 \text{ °C}; Fig. 7$                                     | -    | -   | 5   | mA   |
|                       |                                                                                       | $V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G-;$<br>$T_j = 25 \text{ °C; } Fig. 7$                                 | -    | -   | 5   | mA   |
|                       | $V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-;}$<br>$T_j = 25 \text{ °C; } Fig. 7$ | -                                                                                                                       | -    | 5   | mA  |      |
| IL                    | latching current                                                                      | $V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T2+ G+;$<br>$T_j = 25 \text{ °C}; Fig. 8$                                     | -    | -   | 10  | mA   |
|                       |                                                                                       | $V_D = 12 \text{ V; } I_G = 0.1 \text{ A; } T2+ \text{ G-;}$<br>$T_j = 25 \text{ °C; } \underline{\text{Fig. 8}}$       | -    | -   | 15  | mA   |
|                       |                                                                                       | $V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{ T2- G-};$<br>$T_j = 25 ^{\circ}\text{C}; \text{ Fig. 8}$               | -    | -   | 15  | mA   |
| I <sub>H</sub>        | holding current                                                                       | V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>                                                            | -    | -   | 10  | mA   |
| V <sub>T</sub>        | on-state voltage                                                                      | I <sub>T</sub> = 15 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>                                                           | -    | 1.3 | 1.6 | V    |
| V <sub>GT</sub>       | gate trigger voltage                                                                  | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$<br>Fig. 11                                              | -    | 0.8 | 1   | V    |
|                       |                                                                                       | V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 125 °C;<br>Fig. 11                                     | 0.25 | 0.4 | -   | V    |
| I <sub>D</sub>        | off-state current                                                                     | V <sub>D</sub> = 600 V; T <sub>j</sub> = 125 °C                                                                         | -    | 0.1 | 0.5 | mA   |
| Dynamic c             | haracteristics                                                                        |                                                                                                                         | ·    |     |     |      |
| dV <sub>D</sub> /dt   | rate of rise of off-state voltage                                                     | $V_{DM}$ = 402 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit              | 20   | -   | -   | V/µs |
| dl <sub>com</sub> /dt | rate of change of commutating current                                                 | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 12 A; $dV_{com}/dt$ = 20 V/µs; (snubberless condition); gate open circuit | 1    | -   | -   | A/ms |
|                       |                                                                                       | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 12 A; $dV_{com}/dt$ = 10 V/µs; gate open circuit                          | 1.5  | -   | -   | A/ms |
|                       |                                                                                       | $V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 12 A; $dV_{com}/dt$ = 1 V/µs; gate open circuit                           | 4.5  | -   | -   | A/ms |

**3Q Hi-Com Triac** 

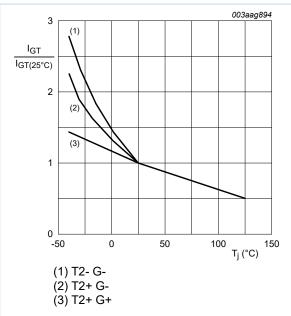


Fig. 7. Normalized gate trigger current as a function of junction temperature

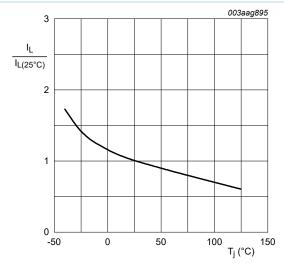


Fig. 8. Normalized latching current as a function of junction temperature

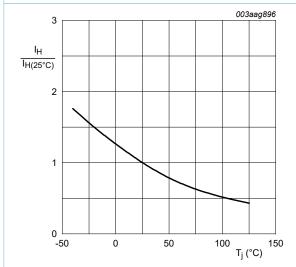
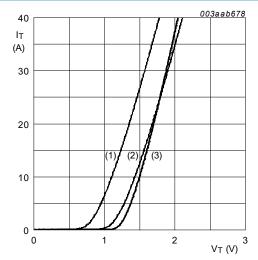


Fig. 9. Normalized holding current as a function of junction temperature



 $V_o$  = 1.164 V;  $R_s$  = 0.027 Ω (1)  $T_j$  = 125 °C; typical values (2)  $T_j$  = 125 °C; maximum values (3)  $T_j$  = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

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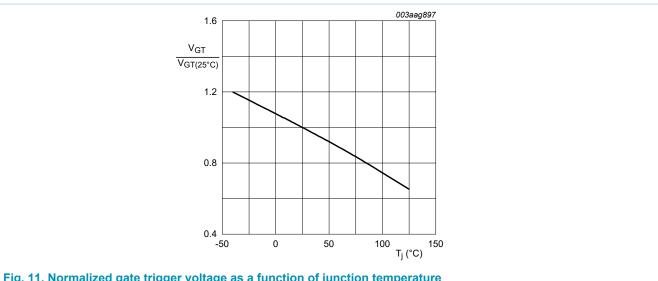
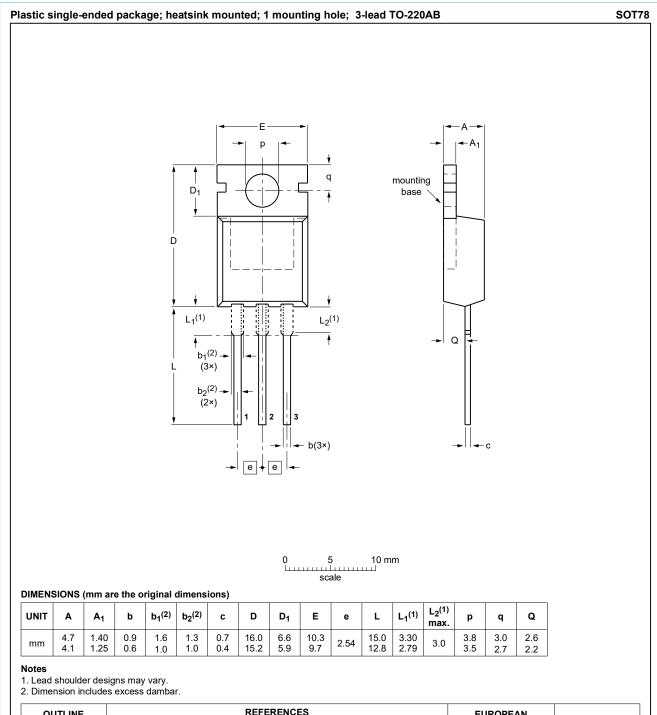


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

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# 10. Package outline



| OUTLINE |     | REFERENCES      |       |  | EUROPEAN   | ISSUE DATE                      |  |
|---------|-----|-----------------|-------|--|------------|---------------------------------|--|
| VERSION | IEC | JEDEC           | JEITA |  | PROJECTION | ISSUE DATE                      |  |
| SOT78   |     | 3-lead TO-220AB | SC-46 |  |            | <del>08-04-23</del><br>08-06-13 |  |
|         |     |                 |       |  | - 1        |                                 |  |

Fig. 12. Package outline TO-220AB (SOT78)

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## 11. Legal information

#### **Data sheet status**

| Document status [1][2]               | Product status [3] | Definition                                                                            |
|--------------------------------------|--------------------|---------------------------------------------------------------------------------------|
| Objective<br>[short] data<br>sheet   | Development        | This document contains data from the objective specification for product development. |
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- Please consult the most recently issued document before initiating or completing a design.
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**3Q Hi-Com Triac** 

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For more information, please visit: http://www.ween-semi.com
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Date of release: 19 September 2018

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